L Number	Hits	Search Text	DB	Time stamp
1	184	(semiconductor or die or chip or IC) same	USPAT	2004/09/23 23:06
-		heat near shield	001111	2001,03,23 23.00
2	97	(semiconductor or die or chip or IC) with	USPAT	2004/09/23 23:09
3	92	heat near shield (semiconductor or die or chip or IC) with	USPAT	2004/09/23 23:15
		heat adj shield		
-	1	"20040061213"	USPAT; US-PGPUB	2004/09/22 16:24
-	3510	257/678	USPAT; US-PGPUB;	2004/09/21 19:41
-	1194	257/685	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/21 19:57
-	2773	257/686	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/21 20:37
_	2458	257/706	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/21 21:08
_	1157	257/720	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 10:50
_	3775	257/723	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 11:09
_	2547	257/777	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 11:32
_	4116	257/778	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 12:15
_	2643	257/784	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 13:47
-	5	5550711.pn. 5898219.pn. 6201302.pn. 6489676.pn.	DERWENT; IBM_TDB USPAT	2004/09/22 13:38
-	2	6538319.pn. 6737750.pn.	USPAT	2004/09/22 13:44

-	12	6274930.pn.	USPAT;	2004/09/22 13:44
		6340846.pn.	US-PGPUB	
		6376904.pn.		
		6388313.pn.		
		6400007.pn.		
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		6414381.pn.		
1		6424050.pn.		
1		20020004258.pn.	•	
		20020014689.pn.		
]		20020125557.pn.		
		20020125558.pn.		
		20020130404.pn.		
	4700		TIODAM.	2004/09/22 14:06
-	4700	257/787	USPAT;	2004/09/22 14:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	<i>'</i>
-	951	438/122	USPĀT;	2004/09/22 14:22
			US-PGPUB;	1 ' '
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	2154	438/108	USPAT;	2004/09/22 15:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	Į l
			IBM TDB	
_	1018	438/109	USPAT;	2004/09/22 15:23
-	1018	400/103	•	2004/03/22 13:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1_	3797	361/760	USPĀT;	2004/09/22 15:29
	3,3,	3017 100	US-PGPUB;	
			EPO; JPO;	i
			DERWENT;	
			IBM_TDB	, , ,
-	25	"6316838"	USPAT;	2004/09/22 16:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
_	1		USPAT	2004/09/22 15:32
-	1		USPAT	2004/09/22 15:33
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-	1		USPAT	2004/09/22 15:33
ļ - 1	1		USPAT	2004/09/22 15:33
-	1		USPAT	2004/09/22 15:33
-	1		USPAT	2004/09/22 15:34
-	1		USPAT	2004/09/22 15:34
_	1		USPAT	2004/09/22 15:34
_	ī		USPAT	2004/09/22 15:35
_	1		USPAT	2004/09/22 15:35
-			1 ' '	2004/09/22 15:35
_	1		USPAT	
-	1		USPAT	2004/09/22 15:36
-	1		USPAT	2004/09/22 15:36
-	1		USPAT	2004/09/22 15:36
_	1		USPAT	2004/09/22 15:41
_	1 1		USPAT	2004/09/22 15:42
_	l i		USPAT	2004/09/22 15:42
1	_		USPAT	2004/09/22 15:43
	1			
-	1		USPAT	2004/09/22 15:43
-	1		USPAT	2004/09/22 15:43
-	0	"electromagnetic near shield" same heat	USPAT;	2004/09/22 16:25
		near (spread\$3 or sink or transfer or	US-PGPUB	
		dissipation)		
_	535	((electromagnetic or electrical) near	USPAT;	2004/09/22 16:47
	1	shield) and heat near (spread\$3 or sink or	US-PGPUB	
			03-10100	
		transfer or dissipation)	Hann	2004/02/02 15 55
-	131	((electromagnetic or electrical) near	USPAT;	2004/09/22 16:27
		shield) same heat near (spread\$3 or sink	US-PGPUB	
		or transfer or dissipation)		<u> </u>
		· · · · · · · · · · · · · · · · · · ·		

- 13 (((electromagnetic or electrical) near USPAT; 2 shield) same heat near (spread\$3 or sink US-PGPUB	2004/09/22 16:40
shield) same heat near (spreads? or sink IIS-DCDIR	
1	
or transfer or dissipation)) and ("RF" or	
radio near frequence) near (chip or die or	
IC or semiconductor)	
- 0 (((electromagnetic or electrical) near USPAT 2	2004/09/22 16:42
shield) and heat near (spread\$3 or sink or	
transfer or dissipation)) and ("RF" or	
radio near frequence) near (chip or die or	
IC or semiconductor)	
	2004/09/22 16:43
shield) and heat near (spread\$3 or sink or	2004/03/22 10:13
transfer or dissipation)) and ("RF" or	
	-
radio near frequency) near (chip or die or	
IC or semiconductor)	2004/00/00 16 40
	2004/09/22 16:48
shield) and heat near (spread\$3 or sink or	
transfer or dissipation)) and ("RF" or	
radio near frequency) with (chip or die or	
IC or semiconductor)	
- 1884 ((electromagnetic or electrical or EMI) USPAT; 2	2004/09/22 17:02
near shield\$3) and heat near (spread\$3 or US-PGPUB	
sink or transfer or dissipation)	
	2004/09/22 17:01
near shield\$3) and heat near (spread\$3 or	
sink or transfer or dissipation)) and	
("RF" or radio near frequency) with (chip	
or die or IC or semiconductor)	
	2004/09/22 17:03
, , , , , , , , , , , , , , , , , , ,	2004/09/22 17:03
near shield\$3) and heat near (spread\$3 or	
sink or transfer or dissipation)) and	
("RF" or radio near frequency) near (chip	
or die or IC or semiconductor)	
1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	2004/09/22 17:23
with shield\$3) and heat near (spread\$3 or US-PGPUB	
sink or transfer or dissipation)	
	2004/09/22 17:23
with shield\$3) and heat near (spread\$3 or	
sink or transfer or dissipation)) and	
("RF" or radio near frequency) near (chip	
or die or IC or semiconductor)	
- 105 (((electromagnetic or electrical or EMI) USPAT 2	2004/09/22 17:22
with shield\$3) and heat near (spread\$3 or	
sink or transfer or dissipation)) and	
("RF" or radio near frequency) with (chip	
or die or IC or semiconductor)	
	2004/09/22 17:23
with shield\$3) and heat	
	2004/09/23 13:33
with shield\$3) and heat) and ("RF" or	2004/05/25 15:55
radio near frequency) near (chip or die or	
IC or semiconductor) - 0 embedded near ground near plane same heat USPAT 2	2004/09/23 13:35
O Chabbara mout ground mout printe than the contract of the co	2004/03/23 13:35
near dissipation and ground near plane	
with electrical near shield\$3	0004/00/00 15 5
	2004/09/23 13:53
dissipation and ground near plane with	
electrical near shield\$3	
1 2-1 3-4 min trans trans trans trans 3-1-1-1	2004/09/23 14:06
near plane with electrical near shield\$3	
	2004/09/23 14:29
near plane same electrical near shield\$3	
- 30 ground near (plane or layer or film or USPAT 2	2004/09/23 14:29
plate) same heat and ground near plane	
same electrical near shield\$3	
	2004/09/23 14:29
plate) and heat and ground near plane	, ,
same electrical near shield\$3	
	2004/09/23 14:37
1 1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	2007/03/23 14.3/
plate) same heat and ground near (plane	
or layer or film or plate) same electrical near shield\$3	
1 1000 00101014	

		,		
-	29	1 2	USPAT	2004/09/23 14:37
		plate) and heat near dissipat\$3 and ground		
		near (plane or layer or film or plate)		
		same electrical near shield\$3		
-	63	ground near (plane or layer or film or	USPAT	2004/09/23 14:38
		plate) and heat near dissipat\$3 and ground		
		near (plane or layer or film or plate)		
	1	same (electrical or electro\$5 or EMI) near		
		shield\$3		
_	15	ground near (plane or layer or film or	USPAT	2004/09/23 14:43
		plate) same heat near dissipat\$3 and	<u> </u>	
		ground near (plane or layer or film or		
		plate) same (electrical or electro\$5 or		
		EMI) near shield\$3		
_	30		USPAT	2004/09/23 14:54
	30	plate) same heat near dissipat\$3 and	002111	2001,03,20 11.01
		ground near (plane or layer or film or		
	ŀ	plate) same (electrical or electro\$5 or		
		EMI) with shield\$3		
	122		USPAT	2004/09/23 14:55
_	122	plate) same heat and ground near (plane or	OSTAT	2004/03/23 14:33
	ļ	layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3		
	70		USPAT	2004/09/23 14:55
] -	/ / /	plate) with heat and ground near (plane or	USEAL	2004/03/23 14.33
		layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3		
	51		USPAT	2004/09/23 15:02
-	31		USERI	2004/03/23 13.02
		plate) with heat and ground near (plane or layer or film or plate) with (electrical		1
		or electro\$5 or EMI) with shield\$3		
	7.	, , , , , , , , , , , , , , , , , , , ,	USPAT	2004/09/23 15:09
-	/1	(ground near (plane or layer or film or	USPAI	2004/09/23 15:09
İ		plate) same heat and ground near (plane or		
		layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3) not (
		ground near (plane or layer or film or		
		plate) with heat and ground near (plane or		
		layer or film or plate) with (electrical		
	1 .	or electro\$5 or EMI) with shield\$3)		